

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	12	(particulate near insulating near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 13:49
L2	3771	(diameter or radius or size) near10 ((first or second or upper or lower or top or bottom) near2 (dielectric or insulating))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 13:51
L3	104	average near2 (diameter or radius or size) near10 ((first or second or upper or lower or top or bottom) near2 (dielectric or insulating))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 13:51
L4	104	(average near2 (diameter or radius or size)) near10 ((first or second or upper or lower or top or bottom) near2 (dielectric or insulating))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 13:57
L5	2	"4544576".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 13:55
L6	0	"10983658"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 13:55
L7	1	"10/983658"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 13:55
L8	1	11/117331	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:12
L9	61643	((particle or particulate) near5 binder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:12

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L10	35346	((particle or particulate) near5 binder) and ((particle or particulate) near5 (radius or diameter or size))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:13
L11	941	(insulating or dielectric) near10 ((particle or particulate) near5 binder) and ((particle or particulate) near5 (radius or diameter or size))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:13
L12	292	(insulating or dielectric) near10 ((particle or particulate) near5 binder) and ((insulating or dielectric) near10 (particle or particulate) near5 (radius or diameter or size))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:14
L13	16518	(trench or via or opening or hole) with binder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:15
L14	598	(trench or via or opening or hole) with binder with (diameter or radius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:16
L15	38	(trench or via or opening or hole) with binder with (diameter or radius) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:17
L16	324	(trench or via or opening or hole) same binder same (diameter or radius) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:20
L17	128	(trench or via or opening or hole) same binder same (diameter or radius) same silica	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:20
L18	1632172	(trench or via or opening or hole) same binder same (diameter or radius) same silica (particle or particulate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:21

## EAST Search History

L19	65	(trench or via or opening or hole) same binder same (diameter or radius) same silica same (particle or particulate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:23
L20	1903	(silica and sog)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:25
L21	6	(trench near10 (silica and sog))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:25
L22	915	(trench near10 (silica or sog))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:25
L23	74	(trench near10 (silica or sog) near10 (binder or resin or coat or coating or coated))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:29
L24	45	"6291298"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:31
L25	3665	trench and silica and (diameter or radius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:32

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L37	210	(US-20040207083-\$ or US-20040192037-\$ or US-20030176058-\$ or US-20020053717-\$ or US-20010048134-\$ or US-20040241979-\$ or US-20030020149-\$ or US-20020031650-\$ or US-20040016962-\$ or US-20050018737-\$ or US-20020154670-\$ or US-20010042637-\$ or US-20050042776-\$ or US-20040043560-\$ or US-20040031987-\$ or US-20020191661-\$ or US-20020051478-\$ or US-20040079979-\$ or US-20050079681-\$ or US-20040051996-\$ or US-20020060362-\$ or US-20030119307-\$ or US-20030016484-\$ or US-20030113981-\$ or US-20010026961-\$ or US-20010000033-\$).did. or (US-20030218140-\$ or US-20010052425-\$ or US-20060081903-\$ or US-20040183115-\$ or US-20040063277-\$ or US-20050095872-\$ or US-20050085037-\$ or US-20050161811-\$ or US-20020074575-\$ or US-20040082164-\$ or US-20040183142-\$ or US-20020014647-\$ or US-20040071177-\$ or US-20050156218-\$ or US-20050158945-\$ or US-20020160904-\$ or US-20040037338-\$ or US-20040022292-\$ or US-20020175396-\$ or US-20050110077-\$ or US-20020139144-\$ or US-20040012038-\$ or US-20030137009-\$ or US-20030143834-\$ or US-20030190794-\$ or US-20020182824-\$ or US-20050118775-\$).did. or (US-20030129837-\$ or US-20030085473-\$ or US-20050153547-\$ or US-20050142863-\$ or US-20020120700-\$ or	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/05/10 15:32
5/10/07 4:34:40 PM	C:\Documents and Settings\Fredmivv\Documents\EAST\workspaces\10694903_case.wsp					Page 4

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L38	15	l37 and trench and silica and (diameter or radius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:34
L39	7	l37 and trench and silica and (diameter or radius) and (colloid or colloidal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:34
L40	703	semiconductor and trench and silica and (diameter or radius) and (colloid or colloidal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:35
L41	734	semiconductor and ((via or opening or hole or trench) same silica) and (diameter or radius) and (colloid or colloidal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 16:34
L42	100	semiconductor same ((via or opening or hole or trench) same silica) and (diameter or radius) and (colloid or colloidal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:39
L43	15	"4544576"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:39
L44	10	("4544576").URPN.	USPAT	OR	ON	2007/05/10 15:41
L45	246668	((particle or particulate) near5 (size or diameter or radius))	USPAT	OR	ON	2007/05/10 15:42
L46	185	trench same ((particle or particulate) near5 (size or diameter or radius))	USPAT	OR	ON	2007/05/10 15:42
L47	29	trench same (insulating or dielectric) same ((particle or particulate) near5 (size or diameter or radius))	USPAT	OR	ON	2007/05/10 15:44
L48	35	(trench with (colloid or colloidal) with silica)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:48



## EAST Search History

L49	109	(trench same (colloid or colloidal) same silica)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:49
L51	167	((via or opening or hole or opening or groove or trench) same (colloid or colloidal) same silica same (insulating or dielectric or insulation))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:56
L52	32644	(trench near isolation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:57
L53	140	(trench near isolation) with (particle or particulate or grain or granular)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:57
L54	27	(trench near isolation) with (particle or particulate or grain or granular) with (insulating or dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 15:59
L55	153	(trench near isolation) same (particle or particulate or grain or granular) same (insulating or dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 16:02
L56	296	(trench near isolation) and ((colloid or colloidal) near5 silica)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 16:02
L57	150	(trench near isolation) and ((colloid or colloidal) near5 silica) and ((particle or grain) near5 (size or diameter or radius))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 16:32
L58	4897	257/330.ccls. or 257/510.ccls. or 257/513.ccls. or 257/341.ccls. or 257/327.ccls. or 257/304.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 16:32
L59	3	I58 and semiconductor and ((via or opening or hole or trench) same silica) and (diameter or radius) and (colloid or colloidal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/10 16:34